



An applied technology company



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# Capital Structure

## Nanoveu Share Price

ASX – Delayed Quote – AUD  
Nanoveu Limited (NVU.AX)

1D 5D 1M 6M YTD 1Y 5Y All

\$0.033

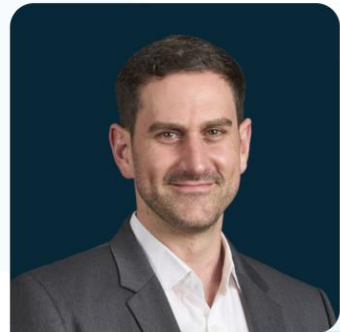


## Capital Structure\*

ASX Code	NVU
Shares on Issue	742.4m
Options on Issue	235.3m
Performance Rights on Issue	157.1m
Previous Close	\$0.035
Average Volume	2.42m
Market Cap	\$25.98m

\*Before issuance of securities from placement on 01/05/25

# Our Board



**DR. DAVID PEVCIC**  
Executive Chairman

- Experienced professional and investor in the resources and technology sector.
- Non-Executive Chairman at Battery Age Minerals Ltd (ASX: BM8).
- Non-Executive Director at Infini Resources Ltd (ASX: I88).
- Holds a Bsc, MBBS, from the university of Western Australia.



**ALFRED CHONG**  
Group Chief Executive Officer

- Founder Of Nanoveu, Has 30+ Years Of Experience In Scaling Companies And Trade Sales.
- Former CEO Of: Atex Media Command (APAC) ,THISS Technologies, 121View.
- Former CMO At 3D International.



**STEVE APEDAILE**  
Non-Executive Director

- 30 Years Of Experience In Accounting.
- Worked At KPMG And Horwath Hong Kong.
- Fellow Of The ICAEW.
- Member Of The AICD.
- Executive Chairman Of Sprintex (ASX:SIX).



**DR. MICHAEL WINLO**  
Non-Executive Director

- Former CEO Of Linear Clinical Research.
- Former Health Lead At Palantir (NYSE:PLTR).
- Holds An MBA From Stanford And An MBBS From UWA.



# Semiconductor Leadership Team



*"We are positioning ourselves to meet growing global demand for low energy but powerful chips driven by the increasing demand for AI-supported applications."*

**Mark Goranson**  
CEO of Semiconductor Technology

## Notable Positions

- Vice President of global operations, TE connectivity (NYSE: TEL).
- Senior Vice President of Fab Operations, ON Semiconductor (NASDAQ: ON).
- Vice President of Fab Operations Freescale Semiconductor (NYSE: FSL).
- Holds a B.Sc. in Physics/Electronics from New Mexico Tech.



*"EMASS's ultra-low-power semiconductor technology has remarkable potential to transform AI enabled hardware, hardware, addressing a critical industry need for more efficient efficient edge computing."*

**Dr. Mohamed M. Aly**  
Founder of EMASS

## Notable Positions

- Associate Professor at NTU Singapore, specializing in AI computing computing systems.
- Former Postdoc at Stanford (2014–2017).
- Senior IEEE Member.
- Collaborated with Stanford and TSMC.
- Recipient of the Nanyang Education Award (2023).
- Holds a Ph.D. from EPFL.



*"NVU's mission to reshape the ultra-low power edge semiconductor landscape through innovation and strategic execution aligns perfectly with my passion"*

**Scott Smyser**  
VP, Sales and Marketing, Semiconductor Technology

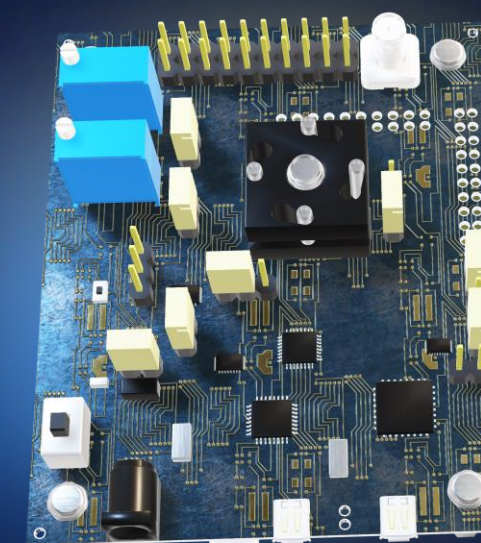
## Notable Positions

- EVP, Worldwide Marketing & Business Development, Si-Ware Systems
- VP & GM, VTI Technologies (Murata)
- SVP of Sales, Atomica
- SVP of Strategic Sales, Rockley Photonics
- Holds an MBA and B.Sc. In Electrical Engineering from University of Southern California





# Semiconductor And System On Chip (SoC) For AI Computing "On The Edge"



The Backbone of Modern Tech – Semiconductors & SoCs power healthcare, automotive, and smart IoT, making devices faster & more intelligent.

Compact & Energy-Efficient – Low-power, high-performance AI processing, perfect for next-gen connected technology.



# Major Sectors Driving Demand for Energy Efficient AI Infrastructure



## Aerospace And Defense

- Drones and UAVs for navigation, video processing and communication
- Military radar and surveillance



## Consumer Electronics

- Smart Phones and Tablets.
- Wearables and Smartwatches.
- Smart TV and appliances.



## Smart Cities

- Robotics and real time control.
- Predictive maintenance to collect and process sensor data on equipment health.



## Healthcare

- Portable diagnostics equipment's
- Imaging Systems like CT and MRI use SoCs for advanced processing



## Energy And Utilities

- Smart Meters for efficient energy resource management
- Optimized solar and wind energy systems



## Data Centers & Cloud Computing

- Unprecedented growth in demand for cloud computing to support AI and ML usage



## Telecommunications

- Networking communications such as Routers and Modems.
- Satellites for space communication.



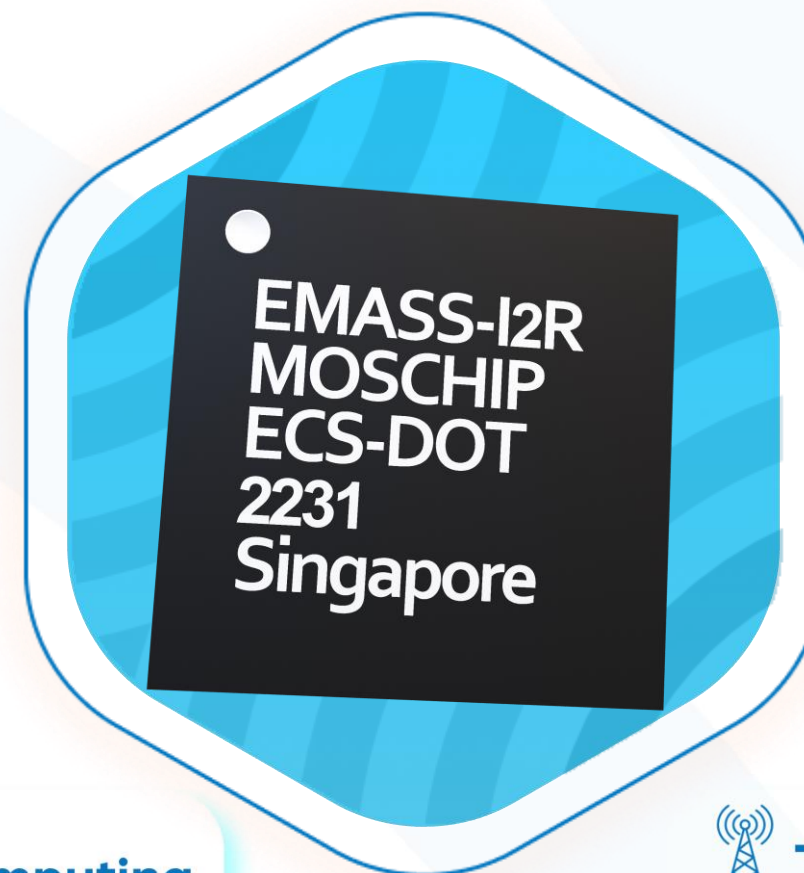
## Automotive

- Optimized Battery Management.
- Seamless Navigation Systems.
- Enable Safe And Intelligent Driving.



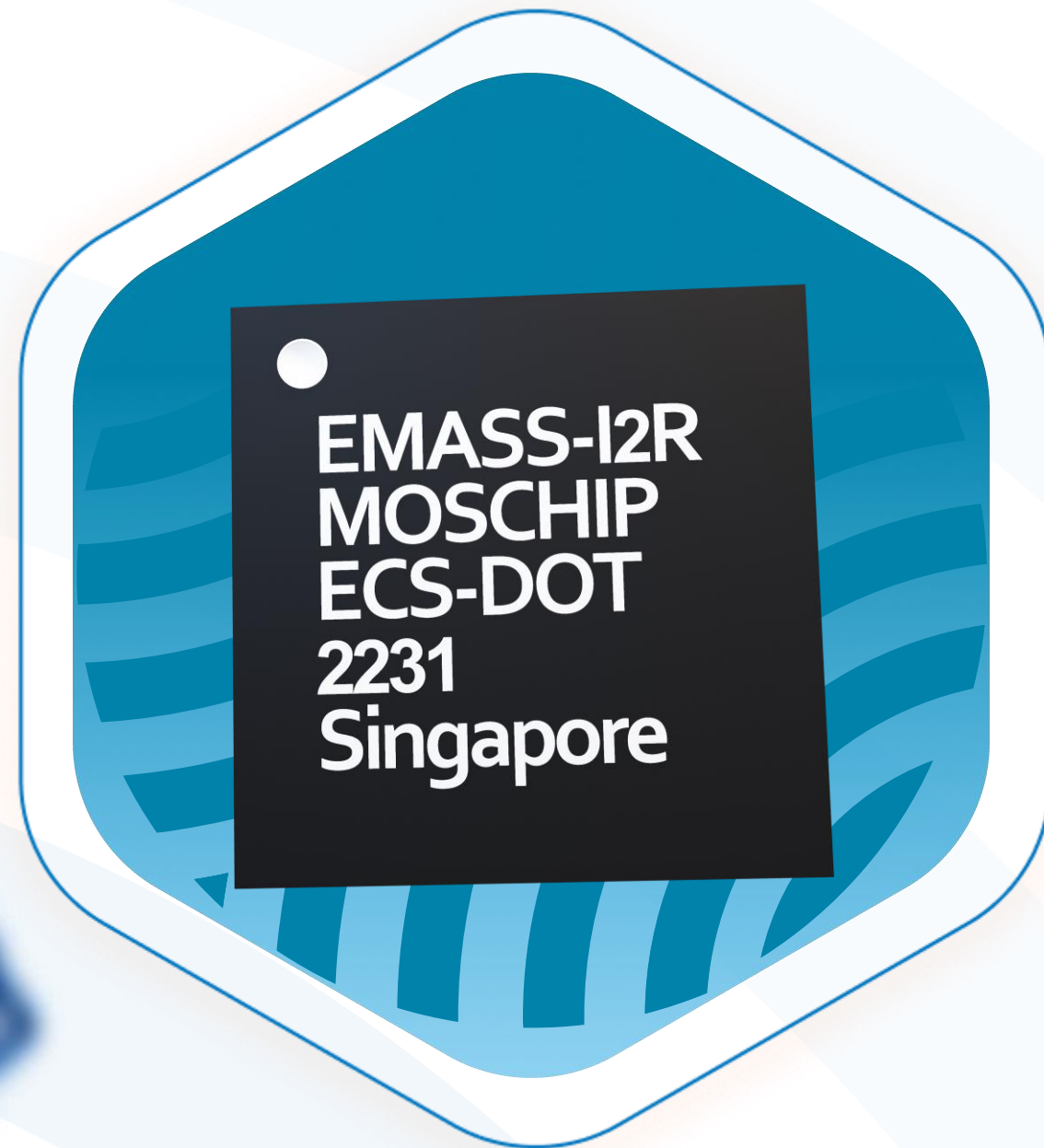
## Gaming & Entertainment

- Used in consoles for graphics and processing.
- VR/AR for immersive experiences.





# The MASS Opportunity



## 1 An SoC With AI Capabilities

- **Problem** – Increasing demand for computational power that can handle AI workloads on the “edge”, faster data processing and analysis
- **Solution** – EMASS’s chip is capable of high AI workloads at its low power and form factor

## 2 Ultra Energy Efficient

- **Problem** – Current Solutions struggle to run AI computations without high power consumption
- **Solution** – EMASS can run AI models efficiently allowing for a wide range of applications

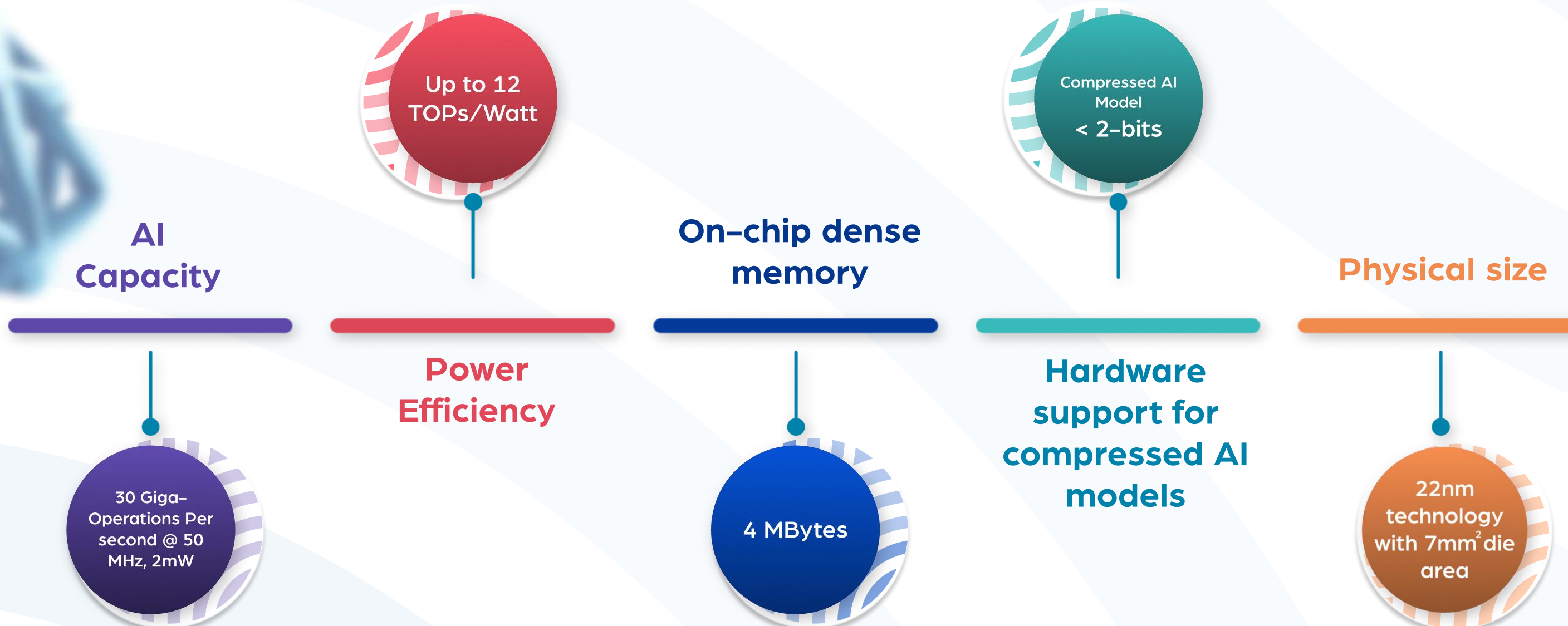
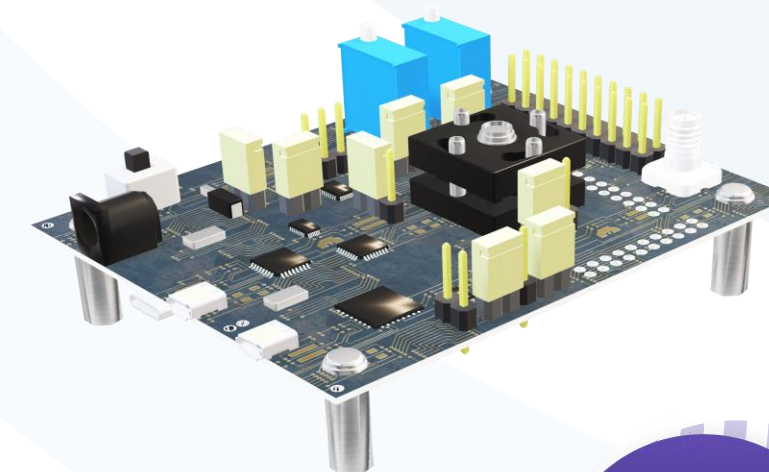
## 3 High Levels Of Interoperability

- **Problem** – Integrating SoCs into edge devices can be complex
- **Solution** – EMASS’s RISC-V architecture is widely accepted with a strong community ensuring seamless integration, and future-proof solutions .



# EMASS Superior Performance, Low Power, Small Form Factor

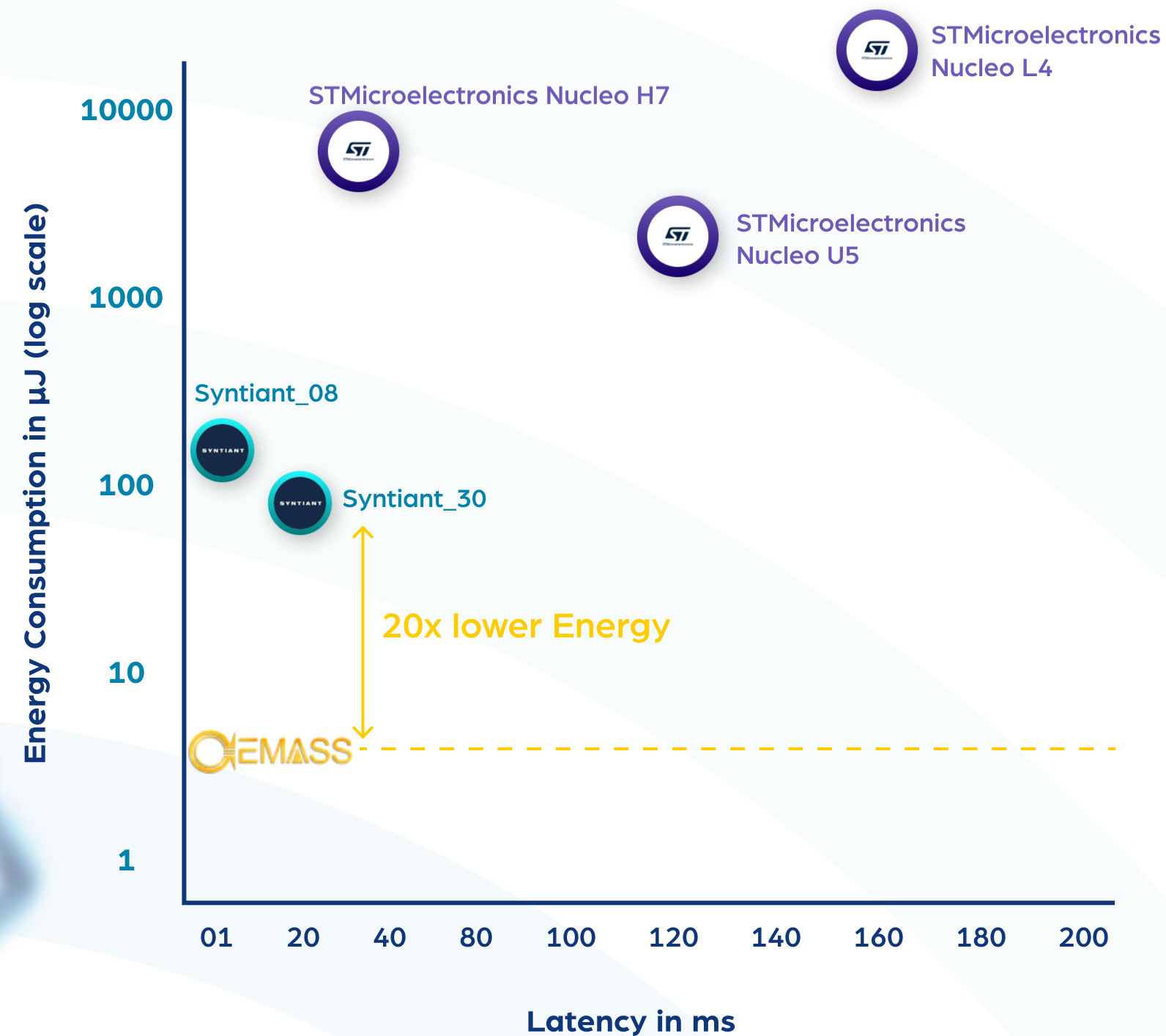
Leveraging The RISC-V Chip Architecture For Efficiency And Interoperability



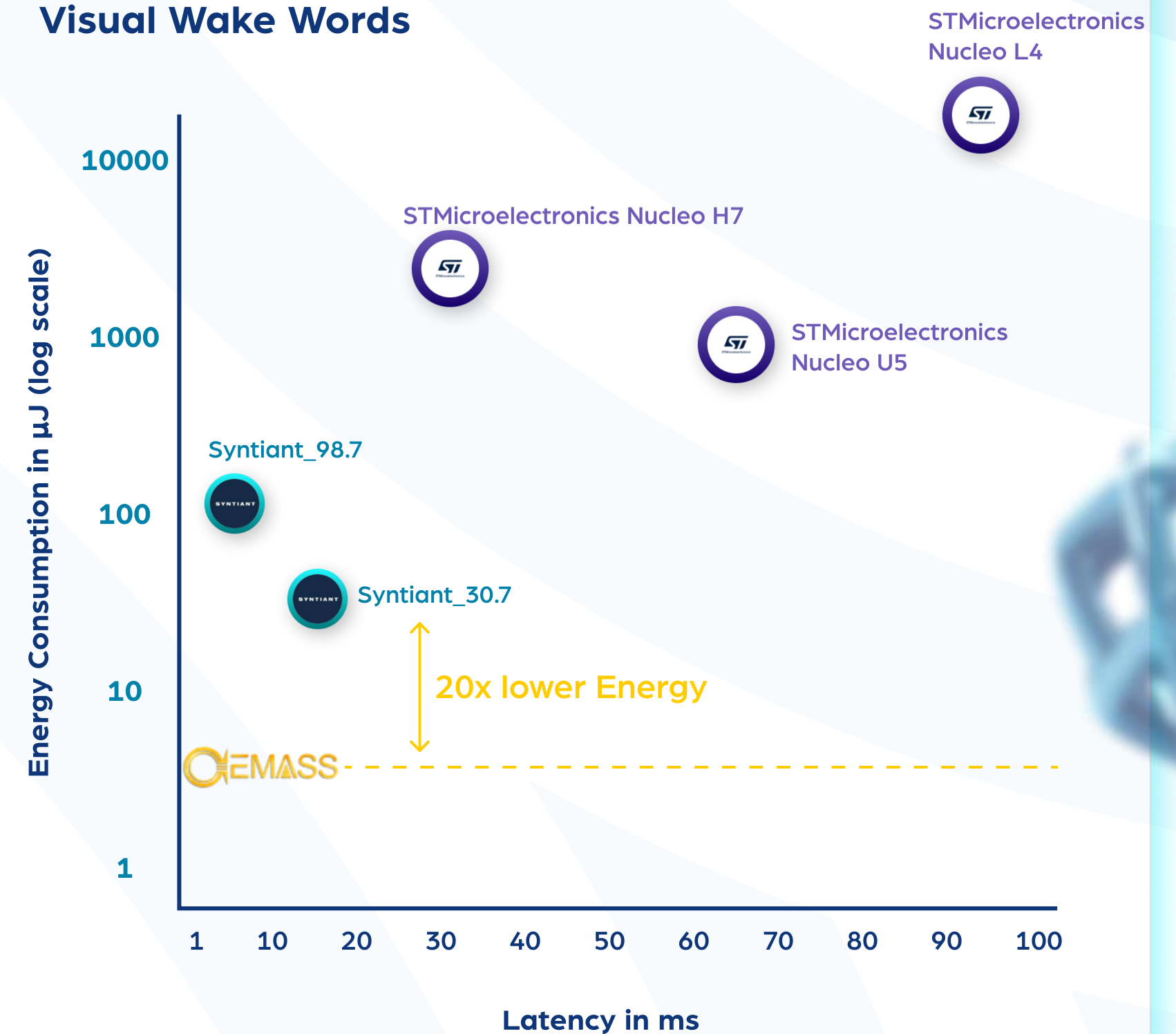
# EMASS Exceptional AI Computation, 20X Lower Energy

EMASS's SOC has greater AI performance compared to today's leading chips

## Image Classification



## Visual Wake Words







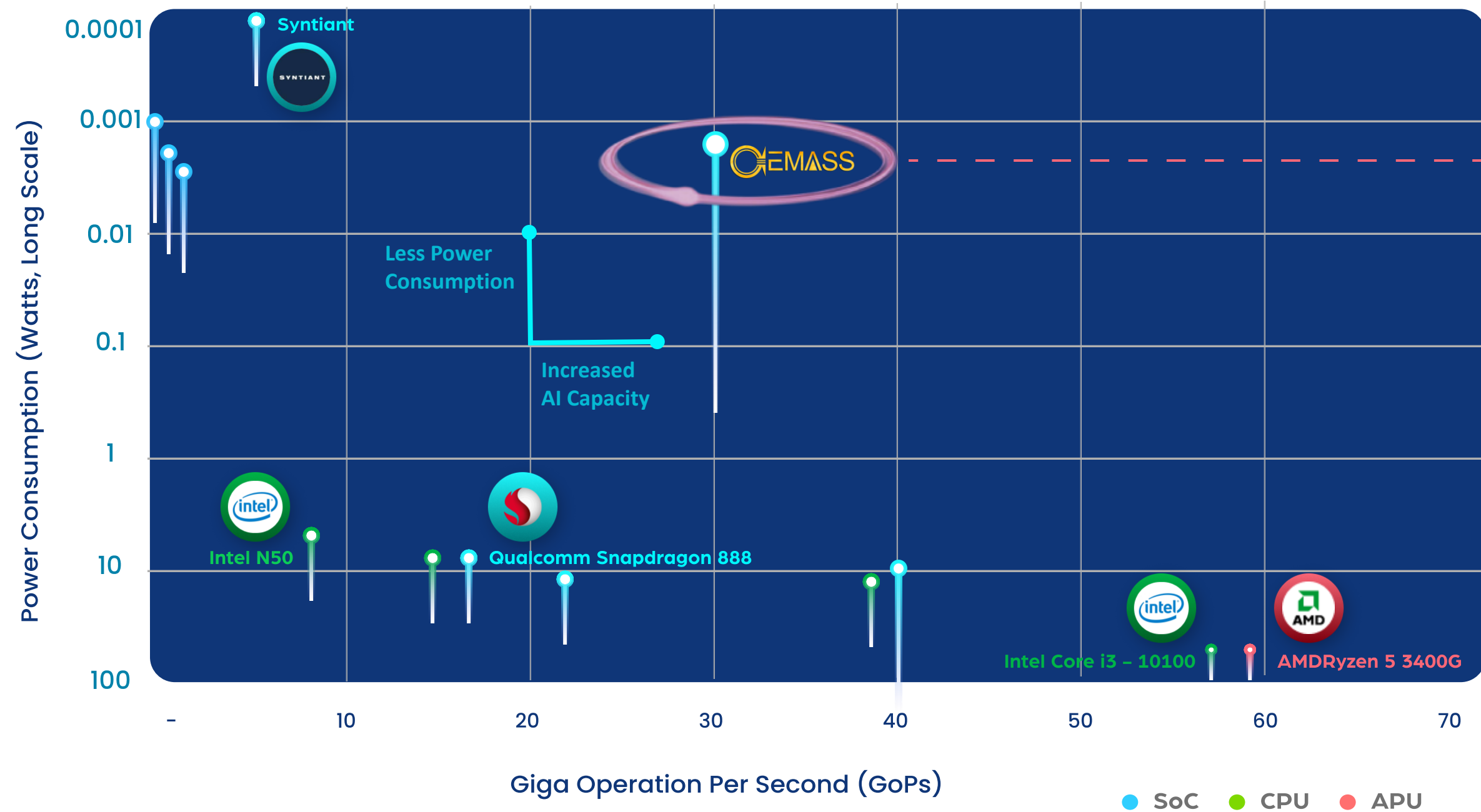
# QEMASS Leads Industry Peers In AI Computation Tasks

Company	Software Optimization	Target Application	AI Performance per Watt (Avg/Peak)	Power (Avg/Peak)	AI Performance	Max AI Parameters
 Nanoveu	YES	3D Vision, Health Monitoring, Wearable, Smart infrastructure	3/15 ToPs	0.1mW/10mW	30 GOPs	13 million
 Maxim Integrated	NO	Medical, Patches, Wearable	1.6/64 GoPs	50mW/2W	3.2 GOPs	3.5 million
 Himax	NO	Vision, Speech, Gesture, Agriculture, Retail	40/320 GoPs	2.5mW/20mW	0.8 GOPs	500 K
 Syntiant	NO	Vision, Smart home, Smartwatches	0.1/1 ToPs	7/30mW	6.4 GOPs	7 Million
 Ambiq	NO	Smart home, Smart watches, Fitness trackers, Animal tracker, Voice remote	240/133 GoPs	1mW/1.8mW	0.24 GOPs	1 Million
 Eta Compute	NO	Vision	200 GoPs	2mW	0.4 GOPs	256 K

\*GoPs  $\approx$  Clock Speed (GHz)  $\times$  Instructions Per Cycle (IPC)  $\times$  Number Of Cores

# EMASS Delivers Exceptional Energy Efficiency

EMASS's SOC has greater AI performance compared to today's leading chips




## EMASS SoC: Power-Efficient AI For Next-Gen IoT

- Complete AI Capability – EMASS SoC delivers full AI operations with top power efficiency.
- Optimized for IoT – Ideal for battery-sensitive devices without performance loss or extra power drain.
- Seamless Integration – No hardware modifications required, enabling next-gen IoT development.



# EMASS Has Leading Energy Efficiency Compared To Peers

## Selected Chip Performances

Company	Chip	Chip Type	Target Industry	Max Performance per Watt	Power Consumption(TBP)	Max Performance
 NANOVEU	EMASS	SOC	IoT, Wearables, Drones Artificial Intelligence	3-15 TOPS	0.1 – 10 MilliWatts	~30 GoPs
 AMD	Ryzen 5 3400G	APU	Computing	~0.91 TOPS	65 Watts	~59 ToPs
 INTEL	Processor N50	CPU	IoT, Chromebook	~0.53 TOPS	75 Watts	~40 ToPs
 ARM	Cortex-A53	CPU	Smartphone, Tablets, Wearables, IoT	~0.0019 TOPS	7.5 Watts	~14 GoPs
 QUALCOMM	Snapdragon 888	SOC	Artificial Intelligence, Wearables, Smartphone	~2.1 TOPS	8 Watts	~17 ToPs
 BROADCOM	BCM2712	CPU	Robotics, industrial automation, edge computing	~3.2 TOPS	12 Watts	~38 ToPs
 MEDIATECH	Helio P60	SOC	Artificial Intelligence Processing, Smartphones	~4 TOPS	10 Watts	~40 ToPs
 MARVELL	Octeon TX2	SOC	5G Networks & Data Centres	~0.67 TOPS	30 Watts	~20 ToPs

\*GoPs ≈ Clock Speed (GHz) × Instructions Per Cycle (IPC) × Number Of Cores

# EMASS Expands Market Opportunities for Nanoveu



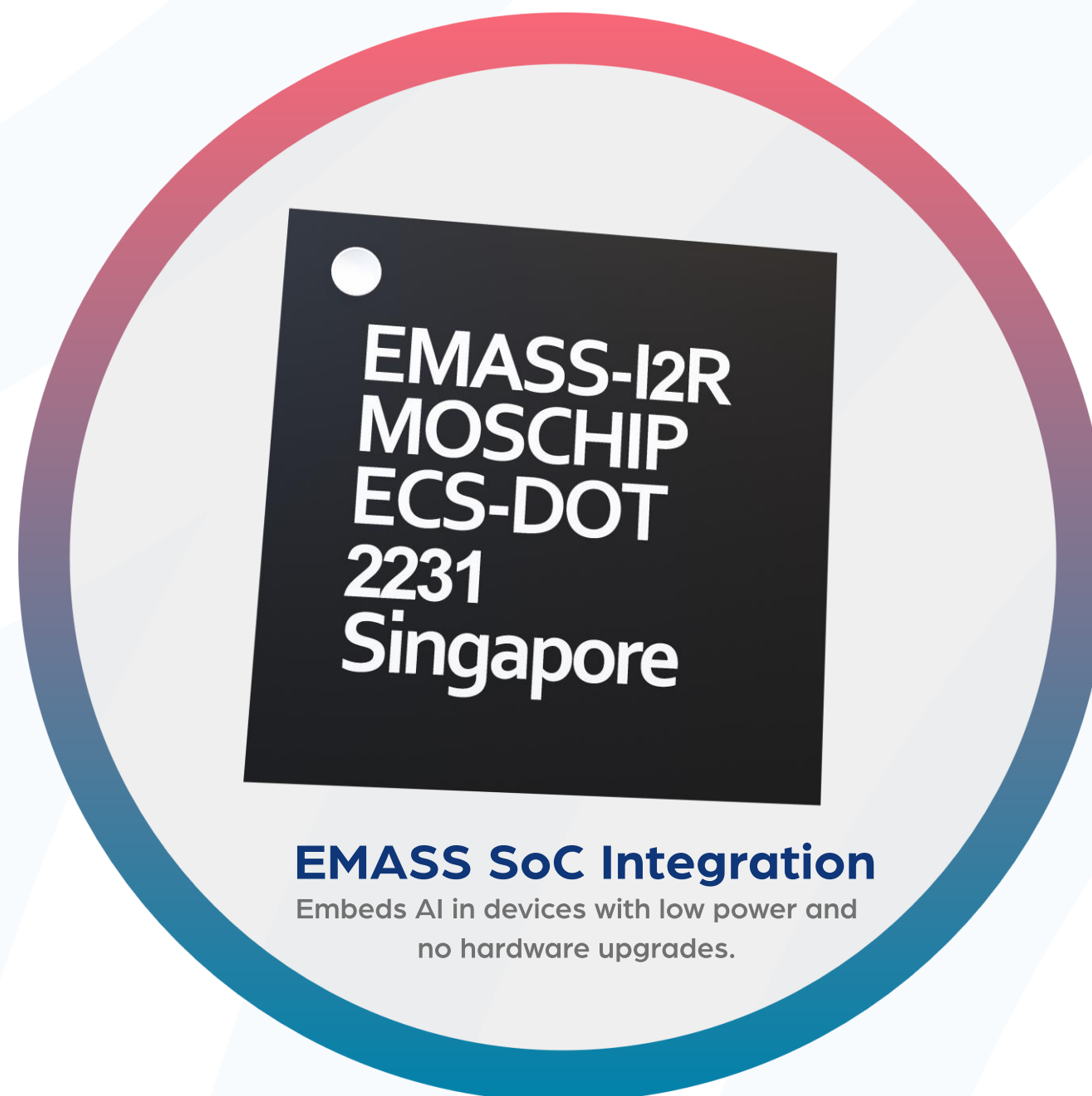
## Smartwatch

- Live Biometric Processing – Non-invasive oxygen, hydration, and blood glucose analysis.
- Predictive Diagnosis – Early disease detection.



## Drones

- AI Self-Navigating Drones – For crop and livestock monitoring.
- Predictive Harvesting – Using multi-spectral and hyper-spectral data



## Medical Devices

- 2D to 3D Models – Instant scans and integrated medical imaging.
- Real-Time Diagnostics – For pacemakers and cochlear implants.



## Glasses & Lens

- 2D to Augmented 3D – Virtual FaceTime and calls.
- Immersive AI Assistant – Enhanced experiences





# Advancing Our Semiconductor Roadmap


Strengthening our position as the leader in ultra-low-power, high-efficiency Edge AI through next-generation IP development


## Strategic Collaboration

Center of  
 x Nanoelectronics & Devices (CND)


 **Strategic Advisor Appointed**  
 Dr. Yehia Ismail (Director, CND) joins as Strategic Advisor to Nanoveu


 **Partnership with CND (Cairo)**  
 Advanced SoC design and nanoelectronics expertise

**Collaborative R&D**  
 Joint development of next-gen edge AI chips on TSMC 16nm

**Strengthening ECS-DoT Platform**  
 Co-developing IP to accelerate innovation and independence

## Defined Technical Goals

 **Cutting-Edge 16nm FinFET Node**  
 Utilising TSMC's advanced 16nm FinFET process for ultra-efficient AI chips

 **Performance-Per-Watt Optimization**  
 Increase energy efficiency and thermal stability


 **Advanced On-Chip Compression**  
 Expand model size with ~1.3bits/weight architecture

 **Scalable Integration Across Devices**  
 Diverse use cases with more advanced AI

## Business Impact & Scalability

 **Strengthening Market Position**  
 Enhanced competitiveness in edge AI hardware.

 **Global Scale & Export Readiness**  
 Chips tailored for fast-growing international markets.

 **Bolstering of IP Portfolio**  
 Expanding proprietary technology to strengthen our competitive moat.

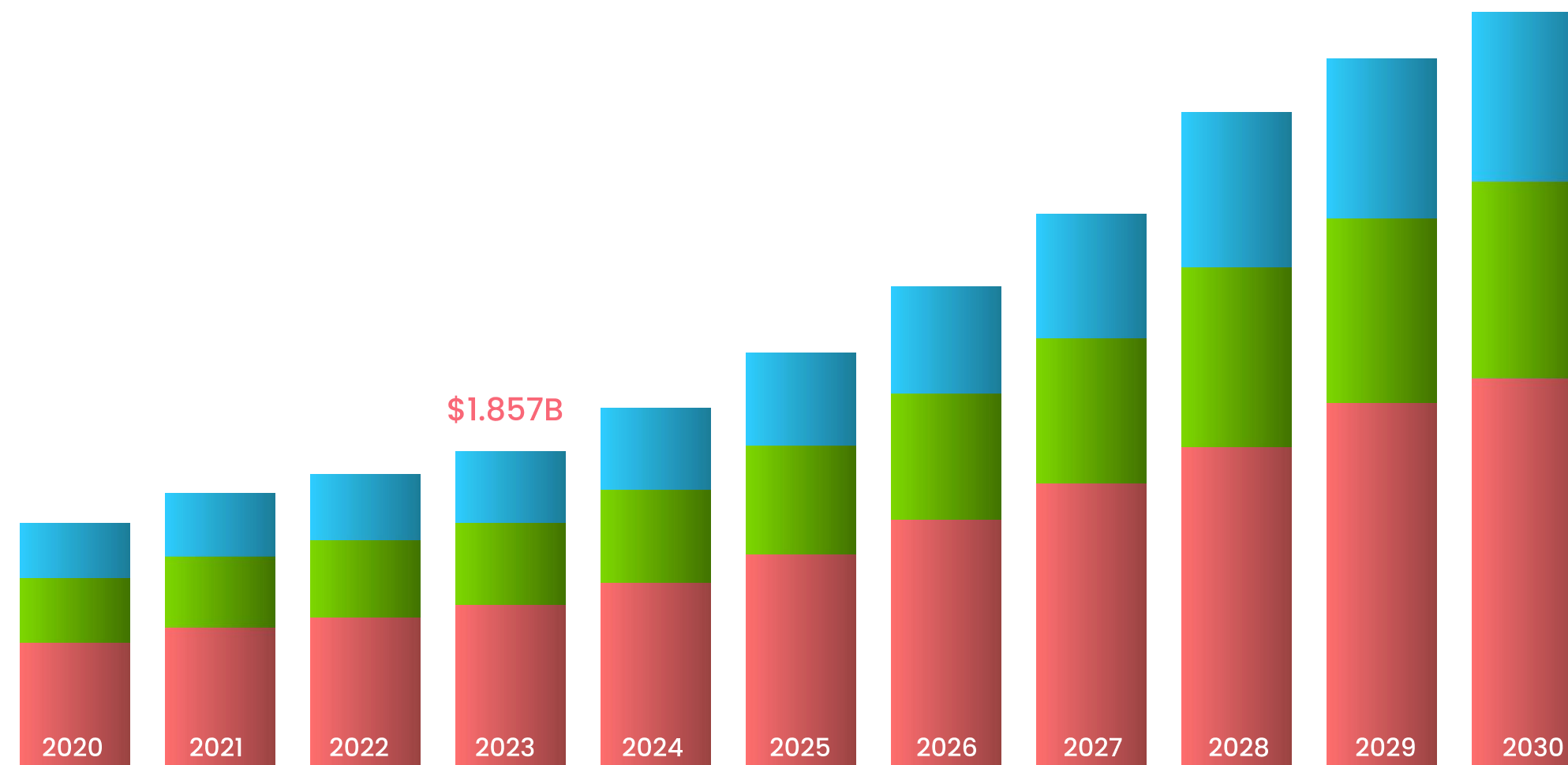
 **Access to Talent & Regional Innovation**  
 Egypt as a launchpad for deeper MENA engagement.

# Semiconductor & SoC Market Set For Rapid Growth

Powering The Future Of AI & Devices

## System On Chip Market Size

By Type 2020–2030 (USD Billion)



Source: Grand View Research

● Digital ● Analog ● Mixed

## SOC Powering The Future Of AI & Devices:

Essential for Next-Gen Tech – SoCs power AI, IoT, and autonomous systems with compact, high-performance computing.

Set to hit  
**\$325.7B**  
**by 2030**

**8.5% Global Market CAGR**

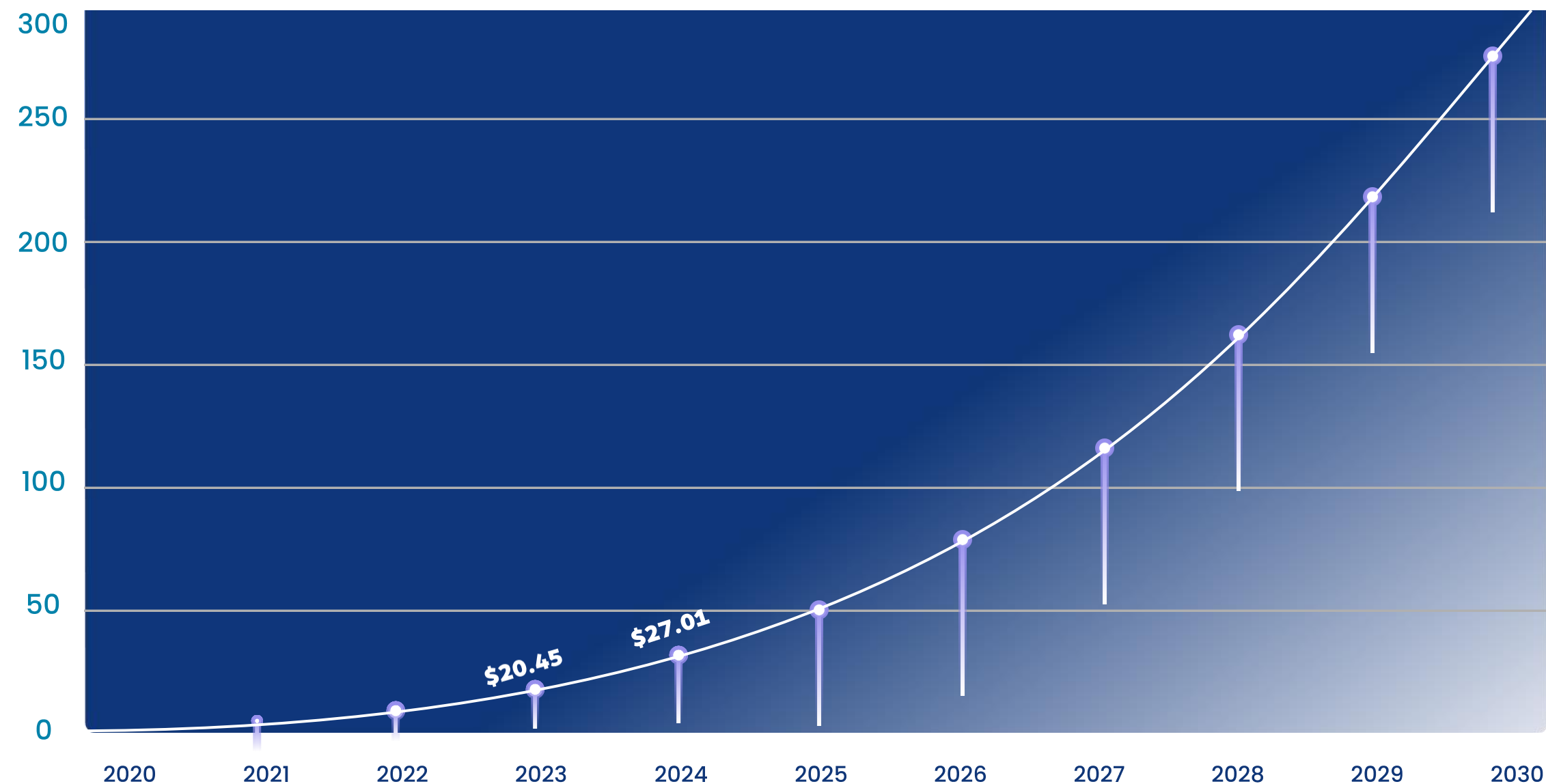
Driven by AI, 5G, and smart devices.



# Poised For Exponential Growth

Edge AI Smart And Efficient Computing For IOT

## Edge AI Growth Rate



Source: Fortune Business Insights

## Edge AI: Smart & Efficient Computing For IoT

Faster, Smarter AI – Powers real-time decisions for IoT, autonomous vehicles, and next-gen tech.

Expected To Reach  
**\$269.82B**  
**by 2030**  
**33.3% CAGR**

As AI moves to on-device processing.

# EMASS Global Development and Collaboration Partners

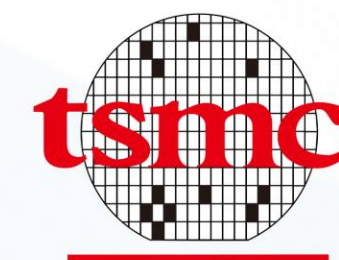
EMASS has been developed with the world's leading Chip manufacturers and partners



**Early Backers, IP & Development**



**ReRAM Collaboration Partner**



Taiwan Semiconductor Manufacturing Company  
Market Cap: \$1.2T



**IC Fabrication, PCB Fabrication, Packaging**





# Thank You

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## Singapore Office

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